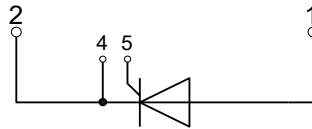
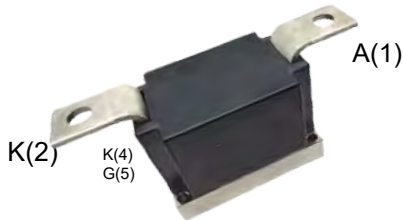


STO860GK16BT

Thyristor Module



Type	V _{RSM} V _{DSM} V	V _{RRM} V _{DRM} V
STO860GK08BT	900	800
STO860GK12BT	1300	1200
STO860GK14BT	1500	1400
STO860GK16BT	1700	1600
STO860GK18BT	1900	1800
STO860GK20BT	2100	2000
STO860GK22BT	2300	2200
STO860GK24BT	2500	2400

Symbol	Test Conditions	Maximum Ratings	Unit
I _{TAV}	T _C =85°C; 180° half sine wave,50HZ	860	A
I _{TRMS}	T _C =85°C; 180° Full cycle sine wave,50HZ	1256	A
I _{TSM}	T _{VJ} =T _{VJM} T _C =25°C	180° half sine wave,50HZ single pulse; V _R =0;	KA
I ² t	T _{VJ} =T _{VJM} T _C =25°C	Gate pulse;20V,5W 1us rise time,500us	A²s .10³
V _{DRM} , V _{RRM}	T _{VJ} =T _{VJM} 180° half sine wave,50HZ ;Gate open	800/2400	V
V _{DSM} , V _{RSM}	T _{VJ} =T _{VJM} 180° half sine wave,50HZ ;single pulse,Gate opent	900/2500	
(di/dt) _{cr}	T _{VJ} =T _{VJM} f=50Hz, t _p =200us V _D =2/3V _{DRM} I _G =1A	repetitive, I _T =960A 100	A/us
	dig/dt=1A/us	non repetitive, I _T =I _{TAVM} 200	
(dv/dt) _{cr}	T _{VJ} =T _{VJM} ; R _{GK} =∞; method 1 (linear voltage rise)	V _{DR} =2/3V _{DRM} 1000	V/us
P _{GM}	T _{VJ} =T _{VJM}	40	W
P _{GAV}	T _{VJ} =T _{VJM}	6	W
V _{RGM}	T _{VJ} =T _{VJM}	5	V
T _{VJ} T _{VJM} T _{stg}		-40...+140 140 -40...+125	°C
V _{ISOL}	50/60Hz, RMS I _{ISOL} ≤1mA	t=1min t=1s 3500 4000	V~
M _d	Mounting torque (M6) Terminal connection torque (M12)	4.5-7/40-60 16-19/142-168	Nm/lb.in.
Weight	typical	1950	g

Sirectifier®

STO860GK16BT

Thyristor Module

Symbol	Test Conditions	Characteristic Values	Unit
I_{RRM}	$T_{VJ}=T_{VJM}; V_R=V_{RRM}$	70	mA
V_T	$I_T=2400A; T_{VJ}=25^{\circ}C$	1.75	V
V_{TO}	For power-loss calculations only ($T_{VJ}=T_{VJM}$)	0.9	V
r_T		0.21	mΩ
V_{GT}	$V_D=12V$ $T_{VJ}=25^{\circ}C$ $T_{VJ}=-40^{\circ}C$	Max 2.5 Max 3.5	V
I_{GT}	$V_D=12V$ $T_{VJ}=25^{\circ}C$ $T_{VJ}=-40^{\circ}C$	Max 300 Max 400	mA
V_{GD}	$T_{VJ}=T_{VJM}; V_D=2/3V_{DRM}$	Max 0.5	V
I_{GD}	$T_{VJ}=T_{VJM}; V_D=2/3V_{DRM}$	Max 10	mA
I_L	$T_{VJ}=25^{\circ}C; t_p=30\mu s; V_D=12V$ $I_G=1A; di_G/dt=1A/\mu s$	Max 1000	mA
I_H	$T_{VJ}=25^{\circ}C; V_D=6V; R_{GK}=\infty$	Max 500	mA
t_{gd}	$T_{VJ}=25^{\circ}C; V_D=1/2V_{DRM}$ $I_G=1A; di_G/dt=1A/\mu s$	Max 10	us
t_q	$T_{VJ}=T_{VJM}; I_T=500A; t_p=200\mu s; -di/dt=10A/\mu s$ $V_R=100V; dv/dt=50V/\mu s; V_D=2/3V_{DRM}$ typ.	200	us
R_{thJC}	DC current	0.0405	K/W
R_{thJK}	DC current	0.01	K/W
ds	Creeping distance on surface	12.7	mm
dA	Creepage distance in air	9.6	mm
a	Maximum allowable acceleration	59.81	m/s ²

FEATURES

- * International standard package
- * Copper base plate
- * Pressure Contact Technology
- * Isolation voltage 4000 V~
- * RoHs compliant

APPLICATIONS

- * Motor control, softstarter
- * Power converter
- * Heat and temperature control for industrial furnaces and chemical processes
- * Lighting control
- * Solid state switches

ADVANTAGES

- * Simple mounting
- * Improved temperature and power cycling
- * Reduced protection circuits



STO860GK16BT

Thyristor Module

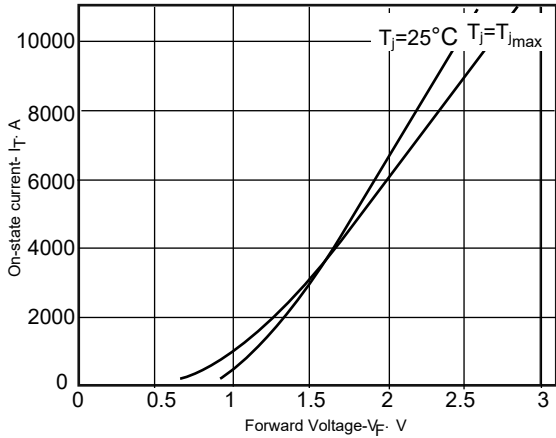


Fig 1 On-state characteristics

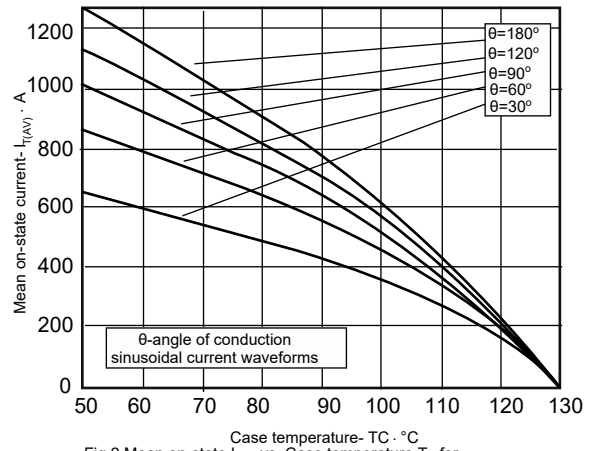


Fig 2 Mean on-state I_{TAV} vs. Case temperature T_C for sinusoidal current waveforms at different conduction angles, $f=50\text{Hz}$

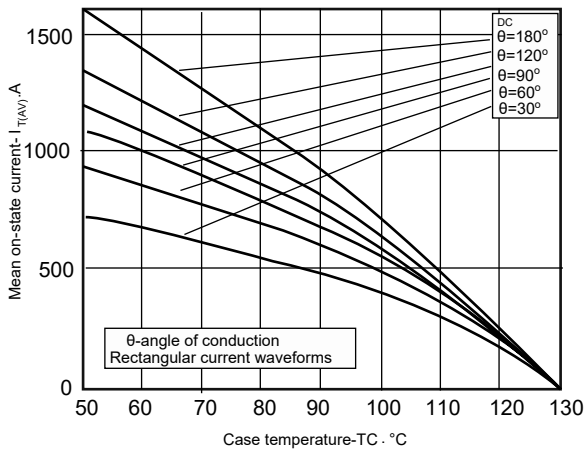


Fig 3 Mean on-state I_{TAV} vs. Case temperature T_C for rectangular current waveforms at different conduction angles and for DC, $f=50\text{Hz}$

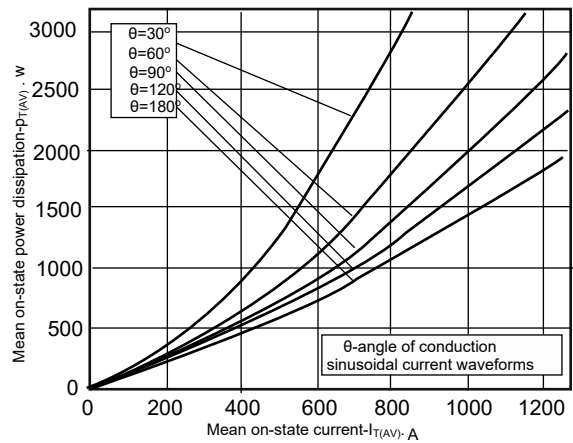


Fig 4 Mean on-state power dissipation P_{TAV} vs. Mean on-state current I_{TAV} for sinusoidal current waveforms at different conduction angles, $f=50\text{Hz}$

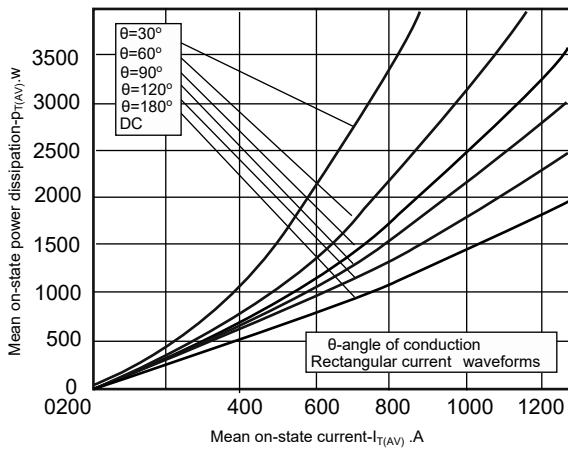


Fig 5 Mean on-state power dissipation P_{TAV} vs. Mean on-state current I_{TAV} for rectangular current waveforms at different conduction angles and for DC, $f=50\text{Hz}$

STO860GK16BT

Thyristor Module

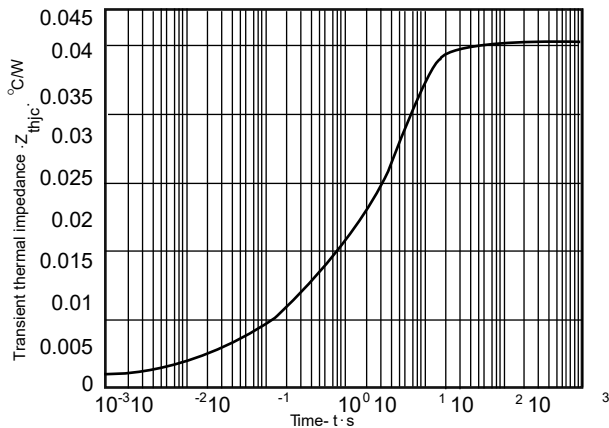


Fig 6 Transient thermal impedance junction to case Z_{thjc} per arm for DC

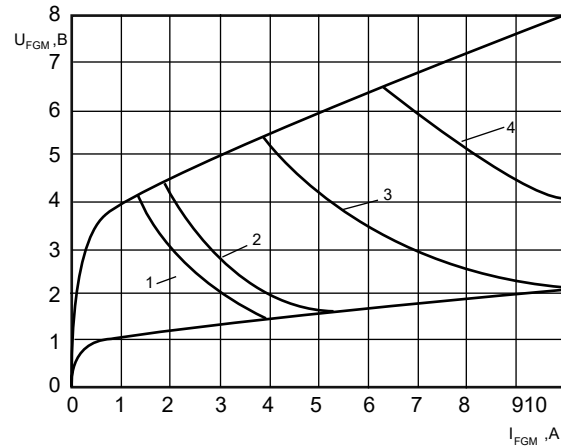


Fig 7 Gate characteristic

Tolerance: +/- 0.5mm

Dimensions in mm (1mm=0.0394")

